

# GL710

## IrDA 1.1 Compliant Infrared Emitting Diode

### ■ Features

1. Compliant with IrDA1.1
2. Compliant with IrDA 1.0, ASK, DASK
3. High radiation intensity  
(MIN. 100mW/sr within±15 degree)
4. High speed (Rise time : TYP. 15ns)

### ■ Applications

1. Personal computers
2. Personal information tools(PDA)
3. Printers

### ■ Absolute Maximum Ratings (Ta=25°C)

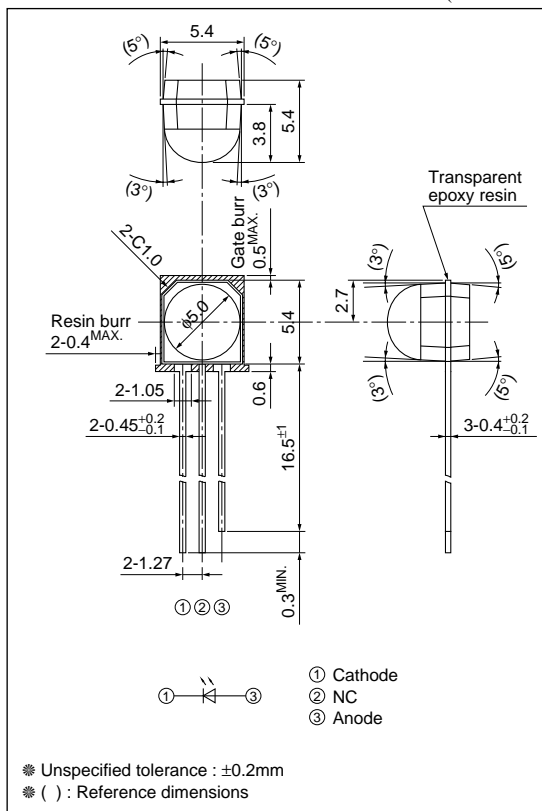
| Parameter                | Symbol    | Rating     | Unit |
|--------------------------|-----------|------------|------|
| Forward current          | $I_F$     | 60         | mA   |
| *1 Peak forward current  | $I_{FM}$  | 0.4        | A    |
| Reverse voltage          | $V_R$     | 4          | V    |
| Operating temperature    | $T_{opr}$ | -20 to +70 | °C   |
| Storage temperature      | $T_{stg}$ | -40 to +85 | °C   |
| *2 Soldering temperature | $T_{sol}$ | 260        | °C   |

\*1 Pulse width 260.4ns, Duty ratio :0.25 or Pulse width 78.1μs, Duty ratio : 3/16

\*2 For MAX. 3s at the position of 1.6mm from the resin edge.

### ■ Outline Dimensions

(Unit : mm)



■ Electro-optical Characteristics

( $T_a=25^\circ\text{C}$ )

| Parameter                    | Symbol          | Conditions  | MIN. | TYP.     | MAX. | Unit           |
|------------------------------|-----------------|---|------|----------|------|----------------|
| Forward voltage              | $V_F$           | $I_f=20\text{mA}$   | —    | 1.3      | 1.9  | V              |
| Peak forward voltage         | $V_{FM}$        | $I_{FM}=0.3\text{A}$ , $t_{WIN}=260.4\text{ns}$ , $DR=0.25$ | —    | 1.9      | 2.8  | V              |
| Reverse current              | $I_R$           | $V_R=3\text{V}$   | —    | —        | 10   | $\mu\text{A}$  |
| Radiant intensity            | $I_E$           | $I_f=0.3\text{A}$ , ${}^{\ast}3\phi\leq 15^\circ$           | 100  | 130      | 300  | $\text{mW/sr}$ |
| Peak emission wavelength     | $\lambda_p$     | $I_f=50\text{mA}$   | 850  | 880      | 900  | nm             |
| Spectrum radiation bandwidth | $\Delta\lambda$ | $I_f=50\text{mA}$   | —    | 40       | —    | nm             |
| Half intensity angle         | $\Delta\theta$  | $I_f=50\text{mA}$   | —    | $\pm 20$ | —    | $^\circ$       |
| Rise time                    | $t_r$           | $I_f=50\text{mA}$   | —    | 15       | 40   | ns             |
| Fall time                    | $t_f$           | $I_f=50\text{mA}$   | —    | 15       | 40   | ns             |

\*3 Direction of mechanical axis of the lens portion :  $\phi=0^\circ$ .

Fig.1 Peak Forward Current vs. Ambient Temperature

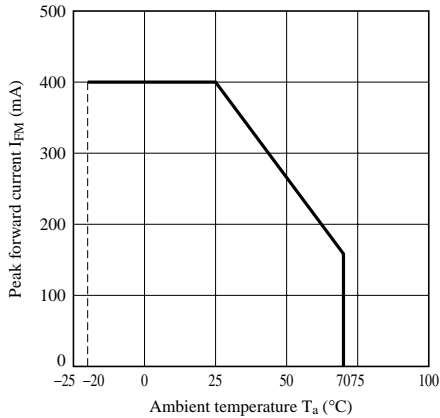


Fig.2 Spectral Distribution

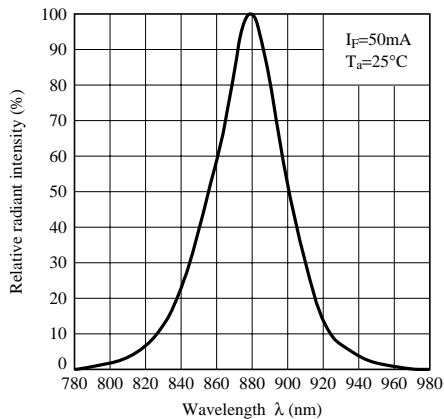


Fig.3 Peak Emission Wavelength vs. Ambient Temperature

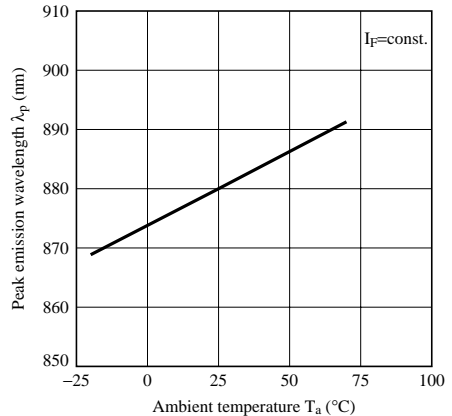


Fig.4 Forward Current vs. Forward Voltage

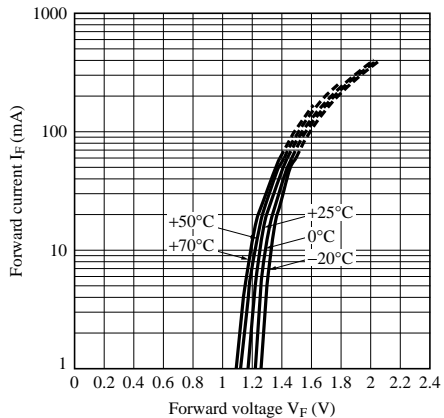


Fig.5 Relative Radiant Intensity vs. Ambient Temperature

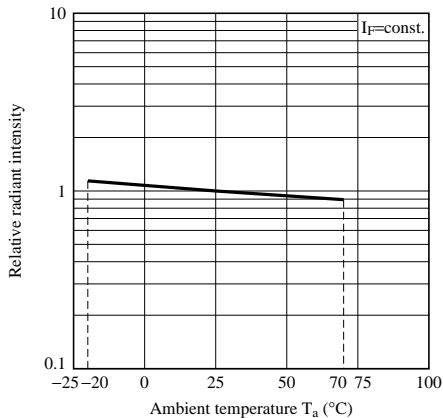


Fig.6 Radiant Intensity vs. Forward Current

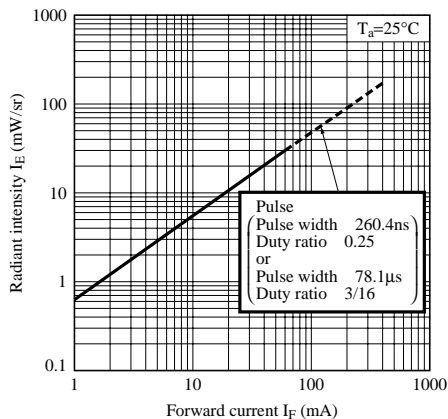
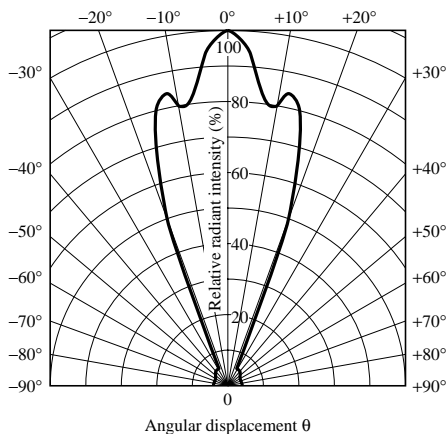


Fig.7 Radiation Diagram



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    - Gas leakage sensor breakers
    - Alarm equipment
    - Various safety devices, etc.
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